UltraTEC[™] Series UT8,12,F2,2525 **Thermoelectric Module**

The UltraTEC[™] Series is a high heat pumping density thermoelectric module (TEM). The module is assembled with a large number of semiconductor couples to achieve a higher heat pumping capacity than standard single stage TEMs.

This product line is available in multiple configurations and is ideal for applications that require higher cooling capacities with limited surface area. Assembled with Bismuth Telluride semiconductor material and thermally conductive Aluminum Oxide ceramics, the UltraTEC[™] Series is designed for higher current and larger heat-pumping applications.

FEATURES **FEATURES**

- High heat pump density
- Precise temperature control
- Reliable solid state operation
- No sound or vibration
- RoHS compliant

APPLICATIONS

- Analytical instrumentation
- Clinical diagnostics
- Photonics laser systems
- Electronic enclosure cooling
- Food and beverage cooling
- Chillers (liquid cooling)

PERFORMANCE SPECIFICATIONS		
Hot side temperature (°C)	25	

Hot side temperature (°C)	25	50
Qmax (watts)	69	75
Delta Tmax (°C)	69	79
Imax (amps)	7.9	7.99
Vmax (volts)	14.4	16.2
Module resistance (ohms)	1.678	1.892

SUFFIX	THICKNESS	FLATNESS & PARALLELISM	HOT FACE	COLD FACE	LEAD LENGTH
11	0.077" +/- 0.015"	0.002" / 0.0035"	Lapped	Lapped	6.0″
TA	0.077" +/- 0.001"	0.001" / 0.001"	Lapped	Lapped	6.0″
ТВ	0.077" +/- 0.0005"	0.0005" / 0.0005"	Lapped	Lapped	6.0″

SUFFIX	SEALANT	COLOR	TEMP RANGE	DESCRIPTION
RT	RTV	White	-60 to 204 °C	Non-corrosive, silicone adhesive sealant
EP	Ероху	Black	-55 to 150 °C	Low density syntactic foam epoxy encapsulant

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• DC operation

TB 0.077" +/- 0.0005" 0.0005" / 0.0005" Lapped Lapped 6.0"	11 TA	0.077" +/- 0.015"	0.002" / 0.0035"	Lapped Lapped	Lapped	6.0"	
TB 0.077 47-0.0005 0.0005 7 0.0005 Lapped Lapped 0.0					Lapped		
	IB	0.077 +/- 0.0005	0.0005 / 0.0005	саррео	Lapped	0.0	

JEALIN				
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Innovative **Technology**

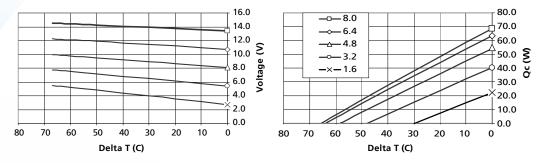
for a Connected World



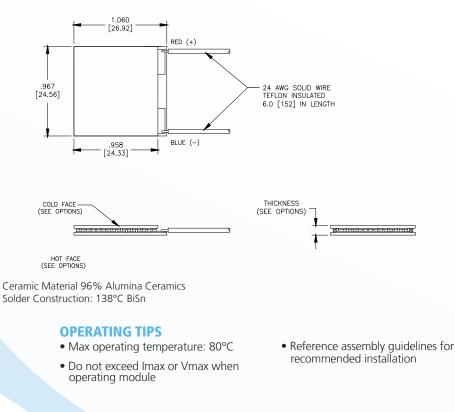
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Innovative **Technology** for a **Connected** World

PERFORMANCE CURVES



MECHANICAL DRAWING



THR-DS-UT8, 12, F2, 2525 1110

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